

## **60V N-Channel Enhancement Mode Power MOSFET**

## **Description**

WMO70N06T1 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

## **Features**

- $V_{DS}$ = 60V,  $I_D$  = 70A  $R_{DS(on)}$  < 7.4m $\Omega$  @  $V_{GS}$  = 10V
- Green Device Available
- Low Gate Charge
- 100% EAS Guaranteed

# **Applications**

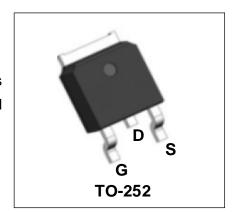
- Battery Management
- UPS
- Motor Control and Drivel

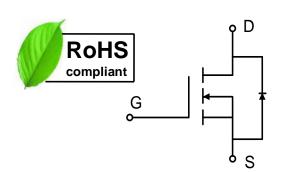
## Absolute Maximum Ratings

Paramatan.		0	Walaa		
Parameter		Symbol	Value	Unit	
Drain-Source Voltage		V <sub>DS</sub>	60	V	
Gate-Source Voltage		V <sub>GS</sub>	±20	V	
Continuous Drain Current@10V1	T <sub>C</sub> =25°C	l <sub>D</sub>	70	Α	
	T <sub>C</sub> =100°C		45		
Pulsed Drain Current <sup>2</sup>		Ірм	308	А	
Single Pulse Avalanche Energy <sup>3</sup>		EAS	151	mJ	
Avalanche Current		las	55	А	
Total Power Dissipation <sup>4</sup>	T <sub>C</sub> =25°C	P <sub>D</sub>	85	W	
Operating Junction and Storage Temperature Range		Тл, Тата	-55 to+150	°C	

## **Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	R <sub>0</sub> JA	60	°C/W
Thermal Resistance from Junction-to-Case <sup>1</sup>	R <sub>eJC</sub>	1.3	°C/W







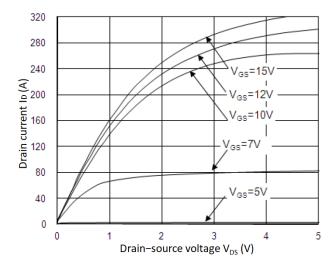
## Electrical Characteristics T<sub>c</sub> = 25°C, unless otherwise noted

Parameter		Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static Characteristics			,	•		l .	
Drain-Source Breakdown Voltage		V <sub>(BR)DSS</sub>	$V_{GS} = 0V, I_{D} = 250\mu A$	60	-	-	V
Gate-body Leakage current		lgss	$V_{DS} = 0V, V_{GS} = \pm 25V$	-	-	±100	nA
Zero Gate Voltage Drain Current	T <sub>J</sub> =25°C	- I <sub>DSS</sub>	V <sub>DS</sub> = 48V, V <sub>GS</sub> = 0V	-	-	1	μA
	T <sub>J</sub> =85°C			-	-	30	
Gate-Threshold Voltage		V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2	3	4	V
Drain-Source On-Resistance <sup>2</sup>		R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 40A	-	5.8	7.4	mΩ
Forward Transconductance		<b>G</b> fs	V <sub>DS</sub> = 10V, I <sub>D</sub> = 30A	-	94	-	S
Dynamic Characteristics	5	<u> </u>				I.	I
Input Capacitance		Ciss			2610	-	
Output Capacitance		Coss	$V_{DS} = 15V, V_{GS} = 0V,$ f = 1MHz	-	881	-	pF
Reverse Transfer Capacitance		Crss	1 – 11411 12	-	290	-	
Switching Characteristic	s	•	,	•			·
Gate Resistance		R <sub>g</sub>	$V_{GS} = 0V$ , $V_{DS} = 0V$ , $f = 1MHz$	-	1.7	-	Ω
Total Gate Charge		Qg	$V_{GS} = 10, V_{DD} = 48V, I_{D} = 25A$	-	50.5	-	nC
Gate-Source Charge		Q <sub>gs</sub>		-	13.2	-	
Gate-Drain Charge		$Q_{gd}$		-	20	-	
Turn-On Delay Time		t <sub>d(on)</sub>	$V_{GS} = 10V, V_{DD} = 30V,$ $R_{G} = 3.3\Omega, I_{D} = 30A$	-	21	-	nS
Rise Time		t <sub>r</sub>		-	37.5	-	
Turn-Off Delay Time		t <sub>d(off)</sub>		-	33	-	
Fall Time		t <sub>f</sub>		-	23.2	-	
Drain-Source Body Diod	e Characte	eristics				ı	I
Diode Forward Voltage <sup>2</sup>		V <sub>SD</sub>	I <sub>F</sub> = 30A, V <sub>GS</sub> = 0V	-	-	1.2	V
Continuous Source Current <sup>1,5</sup>		Is	Vg=Vp=0V,Force Current	-	-	70	Α
Body Diode Reverse Recovery Time		t <sub>rr</sub>		-	12.3	-	nS
Body Diode Reverse Recovery Charge		Qrr	- I <sub>F</sub> = 30A, dl/dt= 100A/μs	-	5	-	nC

#### Notes:

- 1. The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300 \text{us}$  , duty cycle  $\leq 2\%$
- 3. The EAS data shows Max. rating . The test condition is  $V_{\text{DD}}$ =25V,  $V_{\text{GS}}$ =10V, L=0.1mH,  $I_{\text{AS}}$ =55A
- 4.The power dissipation is limited by 150°C  $\,$  junction temperature
- 5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.





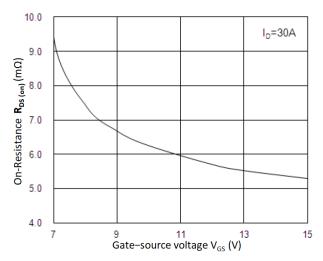
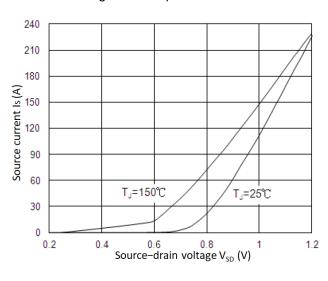


Figure 1. Output Characteristics

Figure 2. R<sub>DS</sub>(on) vs. V<sub>GS</sub>



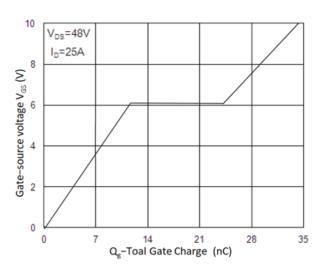
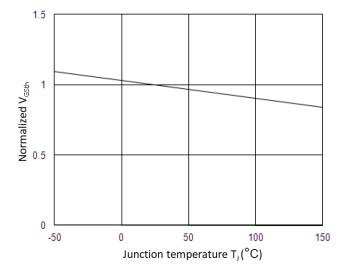


Figure 3. Forward Characteristics of Reverse

Figure 4. Gate Charge Characteristics



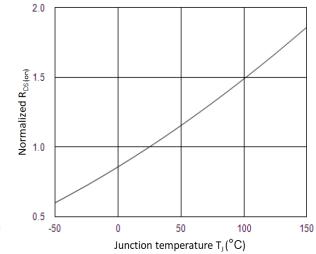
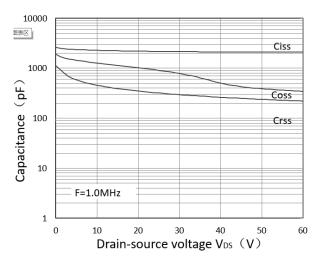


Figure 5. Normalized  $V_{\text{GS(TH)}}$  vs.  $T_J$ 

Figure 6. Normalized R<sub>DS(on)</sub> vs. T<sub>J</sub>





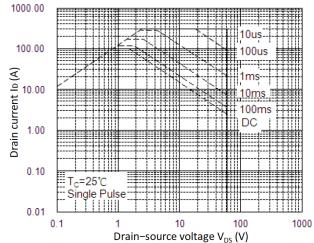


Figure 7. Capacitance Characteristics

Figure 8. Safe Operating Area

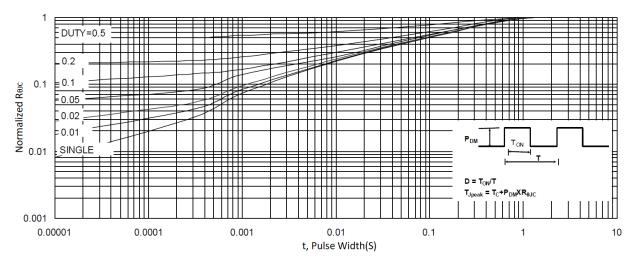
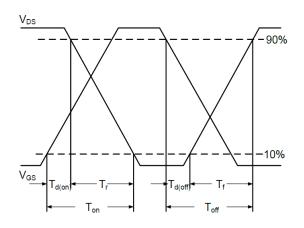


Figure 9. Normalized Maximum Transient Thermal Impedance



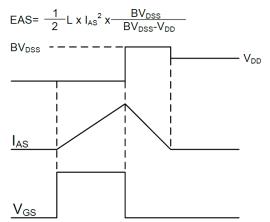


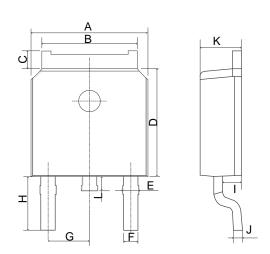
Figure 10. Switching Time Waveform

Figure 11. Unclamped Inductive Switching

Waveform



## **Mechanical Dimensions for TO-252**



## **COMMON DIMENSIONS**

SYMBOL	MM			
	MIN	MAX		
А	6.40	6.80		
В	5.13	5.50		
С	0.88	1.28		
D	5.90	6.22		
E	0.68	1.10		
F	0.68	0.91		
G	2.29REF			
Н	2.90REF			
I	0.85	1.17		
J	0.51REF			
K	2.10	2.50		
L	0.40	1.00		



## **Ordering Information**

Part	Package	Marking	Packing method
WMO70N06T1	TO-252	WMO70N06T1	Tape and Reel

## **Marking Information**



WMO70N06T1 = Device code WWXX XXX= Date code

## **Contact Information**

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